DECLARATION OF COMPLIANCE
- RoHS Declaration -

NXP Semiconductors Netherlands B.V. declares that its semiconductor products (including homogeneous sub-components –pins, casing, and internal parts) are designed to be:

- RoHS compliant and meet the requirements defined under Directive 2011/65/EU of the European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) – recast and its amendments[1]:

RoHS Restricted Substance	Allowable Limit
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE)*	1000 ppm (0.1 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)**	1000 ppm (0.1 weight %)
Butyl benzyl phthalate (BBP)**	1000 ppm (0.1 weight %)
Dibutyl phthalate (DBP)**	1000 ppm (0.1 weight %)
Diisobutyl phthalate (DIBP)**	1000 ppm (0.1 weight %)

* This includes also DecaBromoDiphenylEther (Deca-BDE).

** Restrictions on these substances are not effective prior to 2019.

NXP RoHS compliant semiconductor devices contain no more than 0.1% lead (Pb) by weight per homogeneous material, or else the devices may contain lead (Pb) for uses allowed by the RoHS Directive, as amended. NXP might use any of the following RoHS exemptions for RoHS compliant semiconductor devices:

RoHS Exemption	RoHS Exemption Description
6(c)	Copper alloy containing up to 4% lead by weight.
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Any semiconductor device that NXP has not certified as RoHS compliant will contain lead (Pb) in solders. These products would be RoHS compliant when used in OEM applications covered by the RoHS exemption 7(b) that permits lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling or transmission, as well as network management for telecommunications.

To facilitate customer requirements and to verify NXP semiconductor product compliance, NXP material content information is available here: http://www.nxp.com/chemical-content/search/. For specific product details on former Freescale portfolio devices please contact us at ECO-Products@nxp.com.

[1] Including latest amendment under Commission Delegated Directive (EU) 2015/863 of 31 March 2015.

In determining the RoHS status of its products, NXP relies upon its suppliers' material content data certification for each homogenous material in the product(s) that they or their subcontractors provide. The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for NXP products in original sale condition

Griffin Teggeman
Manager, ECO–Products
NXP Semiconductors